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Pages 1-655
# Table of Contents

## Session A -- Advanced Packaging & System Integration

<table>
<thead>
<tr>
<th>Session</th>
<th>Title</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>A-01</td>
<td>Solder behavior and defect formation in joining process by Al/Ni Self-propagating reaction</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td>Wenbo Zhu, Fengshun Wu, Weisheng Xia, Baihui Wang, Paul Wang, Eric Hou</td>
<td></td>
</tr>
<tr>
<td>A-03</td>
<td>Stud Bump Process for Flip-chip Research</td>
<td>6</td>
</tr>
<tr>
<td></td>
<td>Zheng Zhirong, Cui Song, Ma Lixin</td>
<td></td>
</tr>
<tr>
<td>A-04</td>
<td>High Speed Test Structures for In-line Process of 3D System in Packaging</td>
<td>11</td>
</tr>
<tr>
<td></td>
<td>Guanjian Wang, Zhiyuan Zhu, Yichao Xu, Runiu Fang, Min Miao, Yufeng Jin</td>
<td></td>
</tr>
<tr>
<td>A-07</td>
<td>Wafer level package of Wideband Microwave Transmission System and Integrated Microwave Antenna using BCB/Metal Structure with the Die Embedded in Si Substrate</td>
<td>16</td>
</tr>
<tr>
<td></td>
<td>Tianxi Wang, Mei Han, Gaowei Xu, Le Luo</td>
<td></td>
</tr>
<tr>
<td>A-08</td>
<td>Fabricating processes of free-standing silicon nitride thin film for MEMS devices</td>
<td>23</td>
</tr>
<tr>
<td></td>
<td>Shuai Shi, Xuefang Wang, Chunlin Xu, Jiaojiao Yuan, Jing Fang, Shengwei Jiang, Sheng Liu</td>
<td></td>
</tr>
<tr>
<td>A-09</td>
<td>Fabrication and Measurement of Si-based Inductors Integrated in WLP</td>
<td>27</td>
</tr>
<tr>
<td></td>
<td>Bian Xinhai, Guo Hongyan, Zhang Li, KH Tan, CM Lai</td>
<td></td>
</tr>
<tr>
<td>A-10</td>
<td>Failure of Chip Sized Packaging (CSP) under Coupling Fields of Electrical Current and Thermal Cycle</td>
<td>30</td>
</tr>
<tr>
<td>A-11</td>
<td>A Novel Package-on-package Stacking Technique</td>
<td>34</td>
</tr>
<tr>
<td></td>
<td>Xiaofeng Sun, Maoyun Pan, Yuan Lu, Lixi Wan</td>
<td></td>
</tr>
<tr>
<td>A-12</td>
<td>Research on testing of a microsystem based on SiP</td>
<td>37</td>
</tr>
<tr>
<td></td>
<td>Xiongbo Zhao, Penglong Jiang, Liangliang Liu</td>
<td></td>
</tr>
<tr>
<td>A-13</td>
<td>Design of test structures for electrical and reliability measurements in a 2.5D TSV interposer</td>
<td>41</td>
</tr>
<tr>
<td></td>
<td>Huijuan Wang, Jing Zhou Chongshen Song, Daquan Yu, Fengwei Dai, Daniel Guidotti, Yang Song, Pan Jie, Qiu Delong, He Huimin, Wu Peng, Tianmin Du, Liqiang Cao, Lixi Wan</td>
<td></td>
</tr>
<tr>
<td>A-14</td>
<td>Vacuum Fluid Charging and Packaging Technique for Micro Heat Pipes</td>
<td>46</td>
</tr>
<tr>
<td></td>
<td>Xiao-dong Wang, Liang-liang Zou, Gang Liu, Yi Luo</td>
<td></td>
</tr>
<tr>
<td>A-15</td>
<td>Improved EBG Structure Used to restrain Simultaneous Switching Noise</td>
<td>50</td>
</tr>
<tr>
<td></td>
<td>Liuping Wang, Zhihua Li, Liqiang Cao, Lixi Wan</td>
<td></td>
</tr>
</tbody>
</table>
Effectively Restrain the Synchronous Switch Noise through Attaching EBG And Capacitor

Liuping Wang, Zhihua Li, Liqiang Cao, Lixi Wan

A-18 Flip Chip Assembly With Advanced RDL Technology

Shengmin Wen, KyungRok Park, Patrick Thompson, JeongSeok Lee, HyunJin Park, Dwayne Shirley

A-19 A High-Speed Test Board Design for 40GHz Bandwidth Die

Di Zhang, Baoxia Li, Lixi Wan, Haidong Wang, Yu Sun, Tianmin Du, Qibing Wang, Zhongyao Yu, Liqiang Cao, Daquan Yu

A-20 A 3D package design with cavity substrate and stacked die

Huqin Xie, Jun Li, Jian Song, Fengze Hou, Xuefang Guo, Shuling Wang, Yu Daquan, Cao Liqiang, Lixi Wan

A-21 Modeling and Simulation of Cu TSV electroplating for wafer-level MEMS vacuum packaging

Shuai Shi, Xuefang Wang, Chunlin Xu, Jiaojiao Yuan, Jing Fang, Shengwei Jiang, Sheng Liu

A-22 Investigation of silicon stress around through silicon vias by high efficiency micro-Raman microscopy

Jing Xiangmeng, Yu Daquan, He Hongwen, Dai Fengwei, Su Meiyong

A-23 A New Type of Wafer Level Package Based on Silicon Substrate

Haijie Chen, Hong Xu, Dong Chen, Li Zhang, KH Tan, CM Lai

A-24 A kind of 3D hybrid assembly structure and technology

Dongmei Li, Xiaocheng Feng, Binhao Lian, Quanbin Yao

A-25 Cu-Sn low-temperature stack bonding for 3D packaging

Yaping Lv, Mingxian Cai, Sheng Liu, Mingxiang Chen

A-27 Wideband Noise Isolation of Planar EBG with Embedded Capacitors and Inductors

Baoxia Li, Jing Zhang, Zhiyong Cui, Tianmin Du, Haidong Wang, Lixi Wan, Rong Sun, Shuhui Yu, Suibin Luo

A-28 A Synthetic Jet Heat Sink with Cross-flow for Electronic Cooling

Tilak T Ch, ratilleke, Dibakar Rakshit

A-29 Development of a compact bandpass microstrip filter on low loss ultra-thin Coreless substrate for RF-SiP

Xiaofeng He, Yu Sun, Xia Zhang, Zhongyao Yu, LixiWan

A-30 Fabrication and Analysis of 2D Embedded Passive Devices in PCB

Jing Zhang, Baoxia Li, Lixi Wan, Guidotti Daniel, Liqiang Cao, Zhiyong Cui, Tianmin Du, Hu Hao

A-31 Experimental Study on the Mechanical Reliability of Carbon Nanotubes

Yan Zhang, Ling Wang, Jing-yu Fan, Johan Liu

Session B -- Packaging Materials & Processes
B-02 Effect of Reflow Conditions on the Die Shear Strength in Flip Chip on Board with SAC305 Solder Joints ................................................................. 109

B-03 Influence of Package Failure on IC’s Reliability .................................................................................................................. 114
LIN Xiao-ling, Lian Jian-wen , ZHU Liang-biao

B-04 Study of diffusion mechanism in low-temperature bonding method based on surface Cu microcones .................................................................................................................................................. 118
Yi Huang, Anmin Hu, Jin Xiao, Ming Li

B-05 Three Dimensional Flow Analysis for Incomplete Fill Failure During Matrix Array Transfer Molding of SOT Packages ................................................................................................................... 121
Yejun Zhu, Habin Chen, Jingshen Wu, Ke Xue, Fei Wong, Paul Tsang

B-06 Study on Liquid-Solid Electromigration in Cu/Sn-9Zn/Cu Interconnect Using Synchrotron Radiation Real-Time in Situ Imaging Technology .................................................................................................................................................. 126
Mingliang Huang, Zhijie Zhang, Ning Zhao, Xiaofei Feng

B-07 Improving the Impact Reliability of the Ni-doped Solder Joint by Applying Cu-Zn Under Bump Metallization .................................................................................................................................................. 130
Jenq-Gong Duh, Wei-Yu Chen

B-08 Substrate with Ni/Au microcones surface for wire bonding .......................................................................................... 135
Shixin Gao, Anmin Hu, Ming Li, Kaiyou Qian, Hope Chiu

B-10 CTE Difference Decrease of Epoxy Molding Compound after Molding and after PMC .......... 139
Hongjie Liu, Wei Tan, Lanxia Li, Xingming Cheng, Jianglong Han

B-11 Shearing properties of Low Temperature Cu-In Solid-Liquid Interdiffusion in 3D Package ..... 143
Xin Zhao, Yanhong Tian, Ning Wang,

B-12 Synthesis of Copper Nanowires on the Substrates in Aqueous Solution .......................................................... 148
Yinping Deng, Ning Wang, Huiqin Ling, Ming Li,

B-14 The influence of presetting α-Sn on the transformation of Sn at low temperature ........................................... 152
Xiao-long Zuo, Ai-Ping Xian

B-15 Reliability Evalution of Low-cost Bumping by Laser Jetting Sn-Ag-Cu Solder on Electroless Ni/Au UBM .................................................................................................................................................. 156
Wei Gai, Gaowei Xu, Le Luo

B-18 Development of Sn-Bi systems lead-free solder paste .......................................................................................... 160
Kangning Li, Yongping Lei , Jian Lin, Baoquan Liu, Hailong Bai, Junhu Qin

B-19 Adhesive Wafer Bonding of GaAs/Glass with Benzocyclobutene and Dry Film for GaAs CCD ....... .................................................................................................................................................. 163
B-21 Effect of Different Pretreatments on Through Silicon Via Copper Filling .......................... 169
Shuangfu Wang, Mei Han, Jiaotuo Ye, Le Luo

B-24 Low-Cost High-Reliability Assembly of Thermally Warped PoP with Novel Epoxy Flux on Solder Paste .......................................................... 173
Yi Li, Haiyong Cao, Xue Feng, Huiqin Ling, Ming Li, Jiayuan Sun

B-25 Shock Resistant and Thermally Reliable Low Ag SAC Solder Doped With Mn .................. 182
Ming Hu, Lee Kresge, Ning-Cheng Lee

B-26 Improvement of microstructure and mechanical properties of Sn-58Bi alloy with La2O3 .......... 193
Vahid Goudarzi, Matthew Brown, Weiping Liu, Ning-Cheng Lee, Jeffrey ChangBing Lee,

B-28 Synthesis of tertiary ester epoxy resin and application in reworkable underfill .................. 196
Lai Maobai, Zhang Guoping, Sun Rong

B-29 Research on 0.6 mil Ag-8Au-3Pd Alloy Wire Bonding Process ........................................ 200
Cheng Yin, Rui Guo, Ming Li, Jason Xiao, Eric Lv, Hope Chiu

B-30 The Optimization of Au Wire Bonding Process in Microwave Modules .......................... 205
Han Zongjie, Yan Wei, Jiang Weizhuo, Hao Xinfei

B-31 Preparation of Graphene/Nano-MnO2 Composite and Its Electrochemical Performance as Supercapacitor Electrodes ..................................................... 209
Li-Ming Huang, Chunliang Liu, Dayong Gui, Jianhong Liu

B-32 Light extraction efficiency enhancement of white LEDs by bi-layer phosphor configuration .... 214
Sheng Ding, Chunliang Liu, Dayong Gui, Jianhong Liu

B-33 Study of Glass Metallization and Adhesion Evaluation for TGV Application ...................... 217
Le Chen, Qian Wang, Jian Cai, Guangrui Ma, Yang Hu

B-34 Properties of Porous Copper Filled Electrically Conductive Adhesives ............................. 221
Li-Ngee Ho, Hiroshi Nishikawa

B-35 Interfacial Reactions of Co-electrodeposited Eutectic Au-Sn Solder Bumps on Ni and Cu Substrates .......................................................... 225
Mingliang Huang, Tongxin Zhang, Ning Zhao, Tingting Jiao

B-36 Effect of Chemical Functionalization of Multi-Walled Carbon Nanotubes With 4'-Allyloxy-biphenyl-4-ol on Thermal and Mechanical Properties of Organosilicon Nanocomposites ..................................................... 229
Xue Gao, Dayong Gui, Jianhong Liu

B-37 Assembly Process Simulation of TSV Interposer* ......................................................... 234
B-38 20um Pd- copper Wire Bonding Process Development on ASM Eagle60 AP ........................................ 238
   Ming-chuan Han, Jun Li, Xue-Song Xu, Bei-yue Yan, Mei-Jiang Song.

B-39 Preparation and Characterization of Carbon Nanotube@SiO2 Core-Shell Nanoparticles .......... 242
   Zeng Xiaoliang, Yu Shuhui, Sun Rong, Xu JianBin

B-41 Influences of intermetallic compounds morphologies on fracture behaviors of Sn-3Ag-0.5Cu/Cu
   solder joint .............................................................................................................................................. 247
   L.M. Yang, Z.F. Zhang

B-42 Coarsening of Bi phase and intermetallic layer thickness in Sn-58Bi-X (X=In and Ni) solder joint
   .................................................................................................................................................................. 250
   Omid Mokhtari, Hiroshi Nishikawa

B-43 Thermosonic ball bonding behavior and reliability study of Ag alloy wire ............................. 254
   Santosh Kumar, Hoontae Kwon, Young IL Heo, Seuang Hyun Kim, June Sub Hwang, Jeong Tak Moon

B-44 Phase evolution at the interface of SnAgCu/FeNi solder joint during solid state aging .......... 260
   Zhi-Quan Liu, Hao Zhang, Li Zhang, Hongyan Guo, Chi-Ming Lai

B-46 The Effect of Laser-soldering Parameters on the Sn-Ag-Cu/Cu Interfacial Reaction .................. 264
   Lili An, Haitao Ma, Lin Qu, Jie Wang, Jiahui Liu, Mingliang Huang

B-47 Preparation and Strucutural Characterization of Li2MnSiO4 Synthesized via Sol-Gel Method... 268
   Weiling Chen, Dayong Gui, Jianhong Liu

B-48 Scalable Synthesis of the Mono-dispersed Silver Micro-dendrites and Their Applications in the
   Ultralow Cost Printed Electrically Conductive Adhesives ........................................................................... 273
   Xiaoya Cui, Cheng Yang, Zhexu Zhang, Haoyi Wu, Sumwai Chiang, Zijing Su, Jingping Liu, Feiyu Kang,

B-49 Improvement of the Thermal Conductivity by Surface Iodination ............................................ 280
   Haoyi Wu, Cheng Yang, Sumwai Chiang, Feiyu Kang, Lingwen Kong

B-50 Periodic Pulse Reverse Copper Filling for Void-Free Through-Via Filling ............................... 284

B-52 Electrically conductive adhesives filled with surface modified copper particles ...................... 288
   Wenjun Chen, Dunying Deng, Fei Xiao,

B-53 Fabrication and Microstructure evolution OfPreferred Oriented Nanotwinned Copper By Pulse
   Electroplating for RDL in WLP ................................................................................................................. 292
   Heng Lee, Wenguo Ning, Chunsheng Zhu, Gaowei Xu, Le Luo, Shenwu Tian

B-58 A study of underfill using two kinds of Silica as inorganic filler .............................................. 296
   Wenjie Zhang, Pengli Zhu, Tao Zhao, Rong Sun, Chingping Wong.
B-59 Ag modified carbon nanotubes as filler for thermal interface materials ........................................ 301
Zhi Zhang, Xiaoliang Zeng, Ling Zhang, Pengli Zhu, Kai Zhang, Xianzhu Fu, Rong Sun, Matthew M.F. Yuen, C.P. Wong

B-61 Effect of wetting agent on the properties of thermal grease with Al based fillers .................. 304
Ling Zhang, Zhi Zhang, Pengli Zhu, Kai Zhang, Xianzhu Fu, Rong Sun, Matthew M.F. Yuen, C.P. Wong

B-62 Microstructural Design in Ultrafine Interconnects under Current Stressing .......................... 308
Hua Xiong, Zhiheng Huang, Shan Ren, Yunfei En

B-63 A simple way to prepare large-scale copper nanoparticles for conductive ink in printed electronics ............................................................................................................................................................ 317
Yu Zhang, Pengli Zhu, Rong Sun, Chingping Wong

B-64 Effect of Activators and Surfactants in Halogen-free Fluxes on Wettability of Sn-0.7Cu-0.05Ni Solder on Cu Substrate ........................................................................................................................................ 321
Chang-Zheng Li, Mo-Yang Yan, Min-Bo Zhou, Xiao Ma, Xin-Ping Zhang, Hui Zhang, Qiao-Sheng Ye, Yi-Rong Huang

B-65 Undercooling and Solidification Behavior of Sn-Ag-Cu Solder Balls and Sn-Ag-Cu/UBM Joints.. .................................................................................................................................................................................... 325
Guang-Sui Xu, Jing-Bo Zeng, Min-Bo Zhou, Xin-Ping Zhang

B-66 Phase Field Simulation of Solidification Behavior and Microstructure Evolution of Sn-58Bi/Cu Solder Interconnect During Reflow Soldering Process ................................................................. 330
Wen-Jing Ma, Chang-Bo Ke, Min-Bo Zhou, Xin-Ping Zhang

B-67 Investigation on Reliability of Low-Ag Lead-free Solder Alloy ............................................. 334
Yating Hu, Bing An, Yi Zhang, Yiping Wu

B-68 Simulation of 63Sn-37Pb BGA packaging particle formation based on Pulsated Orifice Ejection Method (POEM) ........................................................................................................................................ 338
L. Zhao, F.M. Xu, D. Lu, W. Dong, Y. Li, A. Kawasaki

B-69 Study of Viscoelastic Effect of EMC on FBGA Block Warpage by FEA Simulation ................ 343
Lin TAN, Jinrui LI, Xiyun CHENG, Qian WANG, Jian CAl, Haijun SHEN, Guoliang YU, TonglongZHANG, Shuidi WANG

B-70 Synthetic and formation mechanism of Cu₆Sn₅ single-crystal layer on Cu pad for UBM application .................................................................................................................................................................................... 347
Zhihao Zhang, Huijun Cao, Mingyu Li

B-71 Preparation and Dielectric Properties of BaTiO₃@PANI filled PVDF composites .................. 351
Qiuting Chen, Shenghui Xie, Shuhui Yu, Rong Sun

B-72 Pure Bottom-up filling process for efficient TSV metallization ............................................. 356
Li Ma, Huaiqin Ling, Ming Li, JiangyanSun, Xianxian Yu, Yanyan Li

B-75 Wetting Behavior of Polymer Liquid in Insulation Process for Through Silicon Via .......... 360
B-76 The No-Load Vacuum Eutectic Solder Die Bonding Process .............................................................. 364
   Jing Linxiao, Chen Xianrong, Feng Xiaocheng, He Jinchun

B-77 The preparation and the reliability study of an anisotropic conductive paste (ACP) for RFID tag inlays’ packaging ................................................................................................................................................ 368
   Xiong-hui Cai, Ai-xia Zhai, Chuan-song Cheng

B-78 The study of cooling process’ effect on the growth of IMC at Sn-3.5Ag/Cu soldering interface........
....................................................................................................................................................................................... 372
   Huijing Zhao, Lin Qu, Hua Li, Ning Zhao, Haitao Ma

B-79 The nucleation of Ag3Sn and the growth orientation relationships with Cu6Sn5 ........................................ 377
   Lin Qu, Haitao Ma, Huijing Zhao, Ning Zhao, Anil Kunwar, Mingliang Huang

B-81 Interfacial Reaction in Cu/Sn/Cu Fine Pitch Interconnect during Soldering ........................................ 382
   Mingliang Huang, Ting Liu, Ning Zhao, Hua Hao

B-84 Industrial advanced carbon nanotubes-based materials for electrostatic discharge packaging .........
....................................................................................................................................................................................... 386
   D. Rousseaux, O. Lhost, P. Lodefier

B-85 Combined Thermal and Hygro Effects on the Degradation of LED Package ...................................... 389
   Xiaosong Ma, G.Q.Zhang,

B-86 Study of EMC for Cu bonding wire applicationPapers/B/B-86.pdf .............................................................. 393
   MASAKATSU MAEDA, HIDETOSHI SEKI

B-87 High-Resolution Wet Etching Technology of Thick Electroless Nickel Alloy Film for MEMS Devices and Packaging ..................................................................................................................... 396
   Y.Zhang, Q.S.Zhu, T. Itoh, R. Maeda, A. Toda

B-88 Effect of Fe addition to Sn-3Ag-0.5Cu solder on interfacial reactions during aging ............................ 400
   Xiaoying Liu, Mingliang Huang, Ning Zhao, Lai Wang,

B-89 Characterization for Graphene as Heat Spreader Using Thermal Imaging Method ............................ 403
   Shirong Huang, Yong Zhang, Shuangxi Sun, Xiaogang Fan, Ling Wang, Yifeng Fu, Yan Zhang, Johan Liu

Session C -- Packaging Design and Modeling

C-01 Optimal Design of Package Structure of The Hybrid Integrated DC/DC Power Module Based on Orthogonal Experimental Method ........................................................................................................ 409
   Weng Jiancheng, He Xiaoli, Liu Ganggang, Zhou Bin, En Yunfei

C-03 Molecular Dynamics Study of Thermal Conductivity in Bismuth Telluride Thin Films .................... 413
   Chunjin Hang, Shaopeng Sun, Panpan Lin, Chunqing Wang
<table>
<thead>
<tr>
<th>C-04</th>
<th>Electrical Simulation of 3X3 TSV Array with Different Signal and Ground Patterns</th>
<th>417</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Cheng PANG, Zhi WANG, Xiaoli REN, Ye PING, Daquan YU,</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-05</th>
<th>A Thixotropic Model for Solving the Flow of the Semi-solid Metal Slurry</th>
<th>421</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Fu Jinlong, Wang Kaikun</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-06</th>
<th>Finite Element Analysis of Wire Bonding Non-stick Issue in Miniaturized Package Development</th>
<th>425</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Weiqiang Li, Haibin Chen, Jingshen Wu, Ke Xue, Fei Wong, Wai Keung Ng, Guangxu Cheng</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-07</th>
<th>Low thermal resistance design for a 2.5D package</th>
<th>431</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Xiaomeng Wu, He Ma, Xiaoyang Liu, Daquan Yu</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-08</th>
<th>Study of Thermal Stress by Numerical Simulation Method on Electronic Package with Power Chip</th>
<th>435</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>WANG Lei, WANG Kaikun, LI Mingrong, ZHANG Xianfeng</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-09</th>
<th>Unsteady-state Analysis of Temperature Field of Electronic Package with Power Chip</th>
<th>439</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>WANG Kaikun, WANG Lei, WANG Lu, WANG Yazhi</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-10</th>
<th>Simulation of Temperature Fields for Cu/Cu Joining Process by Self-propagating Reaction</th>
<th>443</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Baihui Wang, Wenbo Zhu, Weisheng Xia, Hui Liu, Fengshun Wu</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-11</th>
<th>The Influence of a Field-dependent Total Effective Charge Number on the Interfacial Migration Rate and the Phase Growth Behavior During Intermediate Phase Growth with Electromigration present</th>
<th>448</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Peng Zhou</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-12</th>
<th>Analysis of thermal stresses in redistribution layer of WLP with different arrangement of interconnections</th>
<th>453</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Chunsheng Zhu, Wenguo Ning, Jiaotuo Ye, Gaowei Xu, Le Luo</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-13</th>
<th>Study of TSV Leakage Current and Breakdown Voltage</th>
<th>458</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Yichao Xu, Guanjian Wang, Xin Sun, Runiu Fang, Min Miao, Yufeng Jin</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-15</th>
<th>Simulation of Deflection and Stress for MEMS Pressure Sensor Based on Graphene</th>
<th>462</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Shengwei Jiang, Xuefong Wang, Shuai Shi, Jiaojiao Yuan, Jing Fang, Can Gooc, Sheng Liu</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-16</th>
<th>An idealized shape of CuCGA solder joint and its load-carrying advantage</th>
<th>467</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Zhao Zhili, Xu Xirui, Sun Fenglian</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-17</th>
<th>Experimental and Numerical Study of Package Moisture Diffusion</th>
<th>472</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Xiaqiong Li, Jianfei Long</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>C-18</th>
<th>The heat simulation of electronic packing for current sensor</th>
<th>476</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Xingguo Cheng, Zongyang Zhang, Fuan Li, Sheng Liu</td>
<td></td>
</tr>
</tbody>
</table>
C-19 Simulation of TSV copper electrodeposition process with additives ................................................. 480
   Wei Luo, Haiyong Cao, Liming Gao, Ming Li

C-20 Signal-Power Integrity Co-Simulations of High Speed Systems via Chip-Package-PCB Co-analysis Methodology ................................................................. 485
   Wen Jiwei, Jing Weiping

C-22 Electrical-Thermal Co-Simulation for power redistribution layers of Interposer with Through-Silicon Vias ................................................................. 492
   Xiaoli Ren, Cheng Xu, Ye ping, Zhi Wang, Cheng Pang, Daquan Yu

C-23 Study of Equivalent Thermal Modeling and Simulation of 2.5D/3D Stacked Dies Module .......... 498
   Fengwei Dai, Daquan Yu, Jing Zhou, He Ma, Xiaomeng Wu, Xiangmeng Jing, Chongshen Song, Hongwen He,

C-25 A High-speed and Low-power Synchronous and Asynchronous Packaging Circuit Based on Standard Gates Under Four-phase Dual-rail Protocol ................................................. 503
   Ruizhen Wu, Yintang Yang, Li Zhang

C-26 Delamination Analysis and Reliability Design for CMOS Image Sensors Packages* ........... 507
   WU Wei, QIN Fei, ZHU Wenhui

C-27 Finite Element Based DOE Methodology for Thermal Fatigue Reliability Design of Multi-row QFN Packages* ......................................................... 512
   XIA Guofeng, QIN Fei, GAO Cha, AN Tong, ZHU Wenhui

C-28 Thermal Fatigue Reliability Design of Solder Bumps in TSV Interposer Package Based on Finite Element Analysis* ......................................................... 517
   XIA Guofeng, QIN Fei, CHEN Si, AN Tong

C-29 A High-speed and Low-power Synchronous and Asynchronous Packaging Circuit Based On Standard Gates Under Four-phase One-hot Encoding ................................................. 521
   Li Zhang, Ruizhen Wu, Yintang Yang

C-30 Full Channel Simulation for High Speed 2.5D Package with Silicon Interposer .................. 525
   Ye Ping, Zhi Wang, Xiaoyang Liu, Daquan Yu

C-31 Comments on Electromigration Analysis Methods ................................................................. 529

C-34 Preliminary validation of entransy-based thermal management for 3D IC ............................... 535
   Yudan PI, Han SUN, Jie HUANG, Wei WANG, JingCHEN, Yufeng JIN, Bingyang Cao

C-35 Study on the board-level drop test of WLCSP with RDL by finite element analysis ........... 539
   Zhai Xinduo, Wang Jun, Guo Hongyan, Zhang Li

C-36 Evaluation of the Effect of Stress Relief Slots on QFN Strip Warpage using Finite Element
C-39 Crosstalk Analysis of Interconnection Structures Fabricated on Silicon Interposer ........... 547  
He Yi, Liqiang Cao, Jing Zhou, Qibing Wang, Daquan Yu, Lixi Wan

C-40 Temperature-dependant thermal stress analysis of through-silicon-vias during manufacturing process ................................................................. 551
Meiying Su, Xia Zhang, Lixi Wan, Daquan Yu, Xiangmeng Jing, Zhidan Fang, Fengze Hou

C-42 Flip Chip CBGA Package Design and Simulation ............................................................... 555
Xie Wenjun, CaoYusheng, Yao Quanbin

C-43 Cohesive Zone Modeling of Mixed-Mode Delamination Tests ........................................ 559
Bingbing zhang, Daoguo Yang, Leo Emst

C-44 Characterization of the Interfacial Normal Stress between Current Collector and Gas Diffusion Layer in Epoxy Packaging Micro Fuel Cells Using FEM Analysis .................................................. 566
Junsheng Liang, Jie Hu, Lei Zhang, Wenjian Ma

C-45 A Multi-Phase Field Study of the Role of Grain Boundary Diffusion in Growth of Cu6Sn5 Intermetallic Compound during Early Stage of Soldering Reaction .................................................. 572
Chang-Bo Ke, Min-Bo Zhou, Xin-Ping Zhang

C-46 Mechanical behavior investigation of single-walled carbon nanotubes with one vacancy ...... 579
Youkai Chen, Fulong Zhu, Kai Tang, Ying Li, Hengyou Liao, Sheng Liu

C-47 Molecular Dynamics Simulation on Thermal Conductivity of Single-Walled Carbon Nanotubes ................................................................................. 583
Kai Tang, Fulong Zhu, Youkai Chen, Ying Li, Hengyou Liao, Sheng Liu

C-49 The FEM Analysis of Stress and Strain in Stacked Solder Bump under Power Load .......... 587
Chunyue Huang, Guoji Xiong, Ying Liang, Song Wu, Tianming Li

C-50 Hybrid Modeling Method for Power Integrity Simulation and Analysis of Multilayer Electronic Packages ................................................................. 591
Yunyan Zhou, Mingming Song, Yalan Wang, Haiyun Xue, Liqiang Cao, Lixi Wan

C-51 THE INTERCONNECT RELIABILITY CORRELATION WITH DESIGN AND TRANSPORTATION STRESS ................................................................................. 595

C-52 Comprehensive Modeling and Analysis of Copper Wire Bonding Process ........................... 600
DeWen Tian, Ming Li, Janardhanan Pillai Madkumar

C-53 Hygro-thermo-mechanical modeling of LED Luminaires ..................................................... 606
Session D -- High Density Substrate & SMT

D-01 Numerical Simulations Based Thermal Reliability of Power Device Packages ........................................ 635
Kailong Yang, Xueyin Zhang, Ming Li, Ming Chen, Liming Gao

D-02 DFM of Soldering Pad of QFP and DIP for Wave Soldering ................................................................. 642
Yuming Wang, Jianxin Yang, Tianxi Wang

D-03 Suspended of high-Q integrated inductors using wafer level packaging technologies .................. 648
Mei Han, Le Luo, Shuangfu Wang, Tianxi Wang

D-04 Effect of die shape on die tilt in die attach process .............................................................. 651
Huai Zheng, Yiman Wang, Xiaobing Luo, Ling Xu, Sheng Liu

D-05 Microstructure analysis of sputtered copper thin film in packaging substrate ................................. 656
Ping Lyu, Hongkun Yu, Techun Wang

D-06 Ultrasound-assisted brazing of large area Cu/Al dissimilar metals used for package heat dissipation substrate .......................................................... 660
Yong Xiao, Mingyu Li, Jongmyung Kim

D-08 High Reliability Underfill Encapsulated Fine pitch System on Flex Packages ............................. 665
Kelvin Pun, Anupam Sharma, Am, eep Singh, M.N.Islam

Session E -- Advanced Manufacturing Technologies and Packaging Equipment

E-01 Research of Wet Etching in HF-Based Solution to Release SOI-Based Gyroscope
Micro-Structures ................................................................................................................................. 671
Jing Fang, Xuefang Wang, Chang Hu, Zhicheng LV, Shuai Shi, Jiaojiao Yuan, Sheng Liu, Can Gao

E-02 Chemical-Mechanical Polishing of Bulk Tungsten Substrate .......................................................... 676
Jin Luo, Yiming Zhang, Lu Song, Shuhui Chen, Yuan Bian, Tianyu Li, Yilong Hao, Jing Chen

E-03 Oxidation: A Cu Wirebonding Challenge in an Interbond Connection through SSB (Stand-off Stitch Bond) Bonding ........................................................................................................ 679
Allen M. Descartin, Yan Bei Yue, Song Mei Jiang

E-04 Buried Parts Simplify Fine Geometry Electronic Packaging, Interconnect, & Assembly .......... 685
Charles E. Bauer, Herbert J. Neuhaus

E-05 A Flexible Software Architecture for Semiconductor Packaging Equipment ............................... 690
Xiaoli Liu, Jie Huo, Zheng Zhang, Ziyang Liu, Liang Tang

E-06 Fabrication of BGA Solder Balls by Pulsated Orifice Ejection Method ........................................ 694
D. Lu, F.M. Xu, L. Zhao, Y.F. Fu, W. Dong, Y. Tan, A. Kawasaki

E-07 The study on grinding process of flip chip wafers ........................................................................... 698
Xiaobo Zhuang, Binhao Lian, Jinchun He, Xiaocheng Feng

E-08 Studies on Pressure Control of Bonding Process ............................................................................ 702
Tang Liang, Zhuang Wenbo, Ye Leizhi, Wang Zhiyue

E-09 Study on a Novel Bond Head with Proportional Electromagnet in Chip Operation ...................... 707
Ye Lezhi, Zhuang Wenbo, Liu Yaqi, Tang Liang

E-10 Study on Volume Production of Uniform Wafer-Level Micro Glass Cavities by A Chemical Foaming Process (CFP) ........................................................................................................ 711
Yu Zou, Jintang Shang, Yu Ji, Li Zhang, Chiming Lai, Dong Chen, Kim-Hui Chen

E-11 A microreactor chip integrated with focus ultrasonic transducers prepared by a modified Chemical Foaming Process ........................................................................................................ 716
Jiafeng Xu, Jintang Shang

E-12 Microfabricated Low Cost Wafer-Level Spherical Alkali Atom Vapor Cells for Chip-scale Atomic Clock by a Chemical Foaming Process (CFP) .............................................................. 720
Youpeng Chen, Jintang Shang, Yu Ji

E-13 Study on the Influencing Factors of Peeling Strength of Aluminum Nitride DBC Substrates ...... 724
Zhao Dongliang, Gao Ling, Liu Zhiping

E-14 Post-manufacturing Effects of Laser Ablation Process on Ceramic-Polymer Composite Substrates ................................................................................................................................. 728
Ghulam Mehdi, Hu Anyong, Jungang Miao
Dynamic Characteristics Analysis of the Flip Chip Bonding Head Based on Multiple Working Conditions

Wenfeng Gong, Meifa Huang, Leilei Chen, Liang Tang, Lezhi Ye

Simulation Analysis of Jetting Dispenser Based on Two Piezoelectric Stacks

Wenjian Luo, Guiling Deng

Session F -- Quality & Reliability

Key Failure Modes of Solder Joints on HASL PCBs and Root Cause Analysis

Yao Bin, Lu Yudong, Luo Daojun

Three-Dimensional X-Ray Laminography and Application in Failure Analysis for System in Package (SiP)

Yuang Chen, Na Lin

Shear Strength and Brittle Failure of low-Ag SAC-Bi-Ni Solder Joints during Ball Shear Test

LIU Yang, SUN Fenglian, YANG Miaosen

A Simulation of IGBT Module Under Power Cycling Test Condition

Xueyin Zhang, Kailong Yang, Ming Li, Ming Chen, Liming Gao

Mechanisms of High Power Laser Diode

Lu Guoguang, Lai Canxiong, Huang Yun, En Yunfei

Effects of POSS-Silanol Addition on the Whisker Formation in Sn3.0Ag0.5Cu Pb-Free Solder

Sihan Liu, Limin Ma, Yutian Shu, Yong Zuo, Fu Guo

Cu pumping effect under different annealing conditions

Hongwen He, Chongshen Song, Cheng Xua, Lei Wang, Wenqi Zhang

Effect of High Temperature Thermal Aging on Microstructural Evolution of Sn3Ag0.5Cu/Cu Solder Joints

Hailong Li, Rong An, Mingliang Fu, Chunqing Wang, Mei Zhu, Rui Zhang

Study on moisture-induced corrosion mechanism of copper wire bonding by thermodynamic calculation

Yingzhi Zeng, Kewu Bai, Hongmei Jin

Growth of Cu-Sn intermetallic compounds during isothermal aging processing in electroplated Cu/Sn/Cu system

Na Huang, Anmin Hu, Ming Li

The effects of creep on electromigration behaviors in Sn-based Pb-free solder joints

Yong Zuo, Limin Ma, Ting Wan, Lei Qiao, Sihan Liu, Fu Guo
F-14 Electro-migration of silver alloy wire with its application on bonding ..................................... 789
Shenggang Wang, Liming Gao, Ming Li, Dacheng Huang, Ken Qian, Hope Chiu

F-15 Advanced Failure Analysis Techniques for SiP Defect Location and Mechanism Analysis ..... 794
Na Lin, Yuan Chen, Guoyuan Li

F-16 Formation and growth of interfacial intermetallic layers of Sn-8Zn-3Bi-0.3Cr on Cu, Ni and Ni-W substrates .............................................................................................................................................. 798
Jiaxing Liang, Tingbi Luo, Anmin Hu, Ming Li

F-17 The fatigue life analysis of conductive adhesive .................................................................................. 804
Peisheng Liu, Jinxin Huang

F-18 Drop performance research of silver content on the SnAgCu based lead-free solder of joint level .......................................................................................................................................................................................... 809
Peng Gao, Jian Lin, Yongping Lei, Guichen Wen

F-19 A Study on Solder-joints Fall-off Failure of Electroless Nickel/Immersion Gold Pad ........... 814
Wan Zhonghua, Zou Yabing, He Guanghui, Luo Daojun

F-20 Analysis of accelerator consumption in TSV copper electroplating .................................................. 818
Qi Sun, Haiyong Cao, Huiqin Ling, Ming Li

F-21 Dissolution and Precipitation of Ag3Sn Plates in Ultra Fine Solder Joints Using Synchrotron Radiation Real-time Imaging Technology ............................................................................................................. 822
Mingliang Huang, Fan Yang, Ning Zhao, Fei Zhang

F-22 The influence of silver content on the reliability of lead-free solder joints under drop condition .................................................................................................................................................................................. 826
Lei Yongping, Yang Jinli, Lin Jian, Fu hangguang, Liu Baoquan, Bai Hailong, Qin Junhu

F-23 Epitaxial growth of intermetallic compounds formed at eutectic Sn37Pb/polycrystalline Cu interface during solid-state aging .......................................................................................................................... 830
Ming Yang, Mingyu Li, Xin Ma

F-24 The Reliability Study of a High density Multi Chip Packaging with Folding Flexible Substrate .... 835
Wen Yin, Bo Zhang, Yuan Lu, Liao Anmou, Du Tianmin, Shangguan Dongkai,

F-25 Mechanical Property and Reliability of Anisotropic Conductive Adhesive in surface mount applications .................................................................................................................................................................................................. 839

F-26 Accurate Thermal Characterization of a GaN PA MMIC using Thermoreflectance Thermography . 843
J.H.L. Ling, A.A.O. Tay, K.F. Choo

F-27 Influence of rapid thermal cycling on the microstructures of single SnAgCu and SnPb solder
Effect of temperature on failure mode of solder joint under vibration loading condition
Zhang Hongwu, Zhao Tianhao, Liu Yang, Sun Fenglian

Effects of aging time on interfacial fracture behaviors of Sn3.5Ag0.5Cu/Cu joints*
QIN Fei, WANG Xiaoliang, AN Tong

Fracture Mode of the IMC Layer in Solder Joints*
WANG Xuming, QIN Fei, AN Tong

Non-Destructive Testing for Defects in Electronic Package Based on Infrared Thermography*
LIU Chengyan, QIN Fei, BAN Zhaowei

An Improved Way to Measure Thermal Impedance of Insulated Gate Bipolar Transistor (IGBT) Module for Power Electronic Packaging
Guo-Quan Lu, MeiLyu Wang, Yunhui Mei, Xin Li, Lei Wang, Gang Chen, Xu Chen,

Interfacial Reaction and Mechanical Properties of Al/Sn-Zn-Ni/Cu Solder Joints
Mingliang Huang, Xianlin Hou, Haitao Ma, Jie Zhao, Yaochun Yang

Warpage Characteristics of Wafer-Level Package of MEMS with Glass Frit Bonding
Gaowei Xu, Shuangfu Wang, Chunsheng Zhu, Jiaotuo Ye, Wei Gai, Le Luo

Comparison of mechanical properties of lead-free microscale solder joints under tensile and shear loading

Electromigration Failure of SnAgCu Lead-free BGA Package Assembled with SnPb Solder Paste
Yanhong Tian, Baolei Liu, Rui Zhang, Jingkai Qin

Electromigration induced stress in Through-Silicon-Via (TSV)
Fei Su, Zixing Lu, Ping Liu, Weijia Li,

Effects of Pb Content on Solidification Behavior and Microstructure on Mixed Solder Alloy
Wei Xiongfeng, Li Xunping, Zhoubin, Wei Guoqiang

The interfacial microstructure and Kirkendall voids in In-48Sn/Cu solder joint
Fei-fei Tian, Zhi-quan Liu

Effect of Sn grain orientation on polarity effect in Sn–Ag–Cu solder joints during electromigration
Jian-Qiang Chen, Jing-Dong Guo

The Green Material Effect on the Board Level Reliability Qualification of QFN Packages
F-44 A study on reliability of chip scale packages in shock environments ......................................................... 921
Jeffrey Chang
Shuai Chen, Lei Wang, Mingxia Jiang, Jieying Tang

F-45 Effects of DC bias and spacing on migration of sintered nanosilver at high temperatures for power electronic packaging .................................................................................................................. 925
Guo-Quan Lu, Wen Yang, Yunhui Mei, Xin Li, Gang Chen, Xu Chen

F-46 Tin Whisker Growth on Electroplating Sn Bilayer ................................................................. 931
Guo-Quan Lu, Wen Yang, Yunhui Mei, Xin Li, Gang Chen, Xu Chen

F-47 Inelastic Strain Evolution in Solder Joint under Thermal-mechanical Coupled Fatigue Loading ................................................................. 937
Jian LIN, Peng GAO, Yongping LEI, Lan WANG

F-48 Failure Analysis of Au-Ge Solder in Microwave Circuit Packaging ......................................................... 941
Chengjie Jiang, Jia Xi, Fei Xiao, Chuanguo Dou, Heng Yang

F-49 Failure Analysis of Au-Ge Solder in Microwave Circuit Packaging ......................................................... 946
Lili Ma, Xinglin Huang, Jie Zha

F-50 A spatial filtering algorithm in low frequency wavelet domain for X-ray inspection image de-noising ....................................................................................................................... 950
Weiwen Lv, Peng Wang, Bing An, Qiangxiang Wang, Yiping Wu

F-51 Interfacial delamination analysis at chip/underfill interface and investigation of its effect on flip-chip's reliability .................................................................................................................. 954
Xiang Gao, Fei Wang, Sheng Liu

F-52 Effect of Interface Structure on Fatigue Life under Thermal Cycle with SAC305 Solder Joints ................................................................. 959
Xu Yanjun, Wang Liquan, Wu Fengshun, Xia Weisheng, Liu Hui

F-53 Groove structure for stress releasing around TSV ......................................................................................... 965
Han SUN, Yudan PI, Wei WANG, Jing CHENG, Yufeng JIN

F-54 Study of the junction to case thermal resistance test method for IC based on ETM ......................................................... 968
Zhang Hongshuo, Zhao Yuanfu, Yao Quanbin, Cao Yusheng

F-55 Simulation of Bonding Wire Deformation in Random Vibration ......................................................... 972
Peifeng Hu, Yusheng Cao, Binhao Lian, Quanbin Yao

F-56 Research on the Rework Process of the Ceramic BallGrid Array Package ......................................................... 976
Yingzhuo Huang, Bo Huang, Pengrong Lin, Yusheng Cao, Binhao Lian, Quanbin Yao

F-57 Microwave Induced Plasma Decapsulation of Thermally Stressed Multi-tier Copper Wire Bonded

F-58 Research on the Rework Process of the Ceramic BallGrid Array Package ......................................................... 976
Yingzhuo Huang, Bo Huang, Pengrong Lin, Yusheng Cao, Binhao Lian, Quanbin Yao

F-59 Microwave Induced Plasma Decapsulation of Thermally Stressed Multi-tier Copper Wire Bonded
IC Packages .......................................................................................................................................................... 981


F-60 Sensitivity study on a MEMS inclinometer with different packaging thickness ........................................ 987
Yu Yang, Daoguo Yang, Zhen Zhang, Jianzhen Zhong

F-61 The microstructure and shear behaviors of the solder joints with decreasing diameter in WLCSP .......... 991
Xiao Li, Lin Lin, Jun Wang

F-62 Effects of Different Temperature Profile on Solder Joints in PBGA Packages .................................................. 994
Fei Wang, Xiang Gao, Sheng Liu

F-64 Isothermal Aging Effect on Microstructure and Mechanical Properties of Ni/Sn3.0Ag0.5Cu/Ni Interconnects with the Decreasing Height ................................................................. 997
Jing-Bo Zeng, Guang-Sui Xu, Min-Bo Zhou, Xin-Ping Zhang

F-65 Influence of Pre-existing Void in the Solder Joint on Electromigration Behavior of Cu/Sn58Bi/Cu Joints .......................................................... 1005
Wu Yue, Min-Bo Zhou, Hong-Bo Qin, Xiao Ma, Xin-Ping Zhang

F-66 Effect of the Cross-Interaction on the Solidification Behaviors of Ni/Sn-Ag-Cu/Cu Solder Joint ...... 1010
Li Xunping, He Xiaoqi, Xu hui

F-67 Performance and Reliability Study of Pd-coated Copper Wire Bonding on ENEPIG Substrate 1014
Lulu SHI, Qian WANG, Yu CHEN, Lin TAN, Jian CAI, Xin GU, Shuidi WANG, Jingwei LI, Yang HU

F-68 Influence of Geometry of Microbump Interconnects on Thermal Stress and Fatigue Life of Interconnects in Copper Filled Through Silicon Via Structure ........................................... 1019
LHong-Bo Qin, Hui-Hui Yuwen, Min-Bo Zhou, Xin-Ping Zhang

F-69 Geometrical size effect on interfacial reaction of Cu/SAC305/Cu during high-temperature storageaging .......................................................... 1025
Liangliang Luo, Fenglian Sun, Yang Liu

F-70 Reliability of RDL structured Wafer Level Packages .............................................................................. 1029
Jia Xi, Donglun Yang, Lin Bai, Xinduo Zhai, Fei Xiao, Hongyan Guo, Li Zhang, Chi Ming Lai

F-71 Studies on Reliability of a 3D System-in-Package Device ....................................................................... 1033
Jia Xi, Kun Lin, Fei Xiao, Xiaofeng Sun

F-73 Study of Creep Performance of Sn-0.7Ag-0.5Cu-3.5Bi-0.05Ni/Cu by Nanoindentation ............... 1037
Yang Miaosen, Sun Fenglian, Li Xia

F-74 Accelerated Aging Test and Failure Analysis of High Brightness Light Emitting Diodes ...... 1040
Fei Yuan, Kaillin Pan, Shujing Chen, Yu Guo, Na Wei
F-75 Study on PoP reliability with different edge bonding during thermal cycling by finite element methods .......................................................... 1044
Shujing Chen, Kailin Pan, Yu Guo, Fei Yuan, Xin Wang

F-76 Effect of Die-attach Materials and Thickness on the Reliability of HP-LED .......................................................... 1048
Fei Weng, Peng Song, Jinlong Zhang, Jianhua Zhang, Luqiao Yin

F-78 Research on Peel Strength of Flexible Copper Clad Laminate .......................................................... 1053
Jie Shuai, Bing An

F-82 Reliability Analysis of Ceramic Quad Flat Package Under Thermal Cycling Loading Conditions by 3-D Finite Element Method .......................................................... 1057
Qin Jingkai, Gao ling, Ji Chunfeng

F-83 Reliability research on optoelectronics packaging .......................................................... 1061
Fengman Liu, Haiyun Xue, Fei Wan, Fengze Hou, Baoxia Li, Haidong Wang, Binbin Yang, Jian Song, Lixi Wan, Liqiang Cao

F-84 Effects of Temperature and Current Density on (Au,Pd,Ni)Sn4 Redistribution and Ni-P Consumption in Ni/Sn3.0Ag0.5Cu/NEPIG Flip Chip Solder Joints .......................................................... 1064
Leida Chen, Yi Feng, Xiaoyan Liu, Mingliang Huang

F-85 Application of Construction Analysis in MMIC Device Intrinsic Reliability Evaluating ............ 1070
Liu Xin, Fang Wenxiao

F-86 Methodology Development for Counterfeit Component Mitigation .......................................................... 1073
Martin Huehne, Jeffrey ChangBing Lee, Harrison Miles, Mark Schaffer

F-87 Internal Thermal Resistance Test and Analysis of Power Device based on Structure Function........ 1082
Zhou Bin, Li Xunping, Yang Shaohua, He Xiaqi

F-88 Mechanism of Cu6Sn5 layer act as a diffusion barrierlayer .......................................................... 1086
Hua Li, Lin Qu, Huijing Zhao, Ning Zhao, Haitao Ma

F-90 Effect of Liquid-solid Electromigration on Interfacial Reaction in Cu/Sn-9Zn/Cu Solder Joint..1090
Mingliang Huang, Qiang Zhou, Haitao Ma, Jie Zhao

F-92 Drop Failure Modes of A Wafer-Level Chip-Scale Packaging .......................................................... 1094
Mingliang Huang, Shuang Liu, Ning Zhao, Haohui Long, Jianhui Li, Weiqiang Hong

F-93 Reliability Analysis of RGB LED on Low-temperature Thermo-mechanical Coupling Field ......1099
Yu Guo, Kailin Pan, Shujing Chen, Fei Yuan, Tao Lu

F-94 Multi-level University Educations Curriculum and Construction of Microelectronics Packaging and Assembly Specialization .......................................................... 1104
F-95  **Thermal and Hygro Effect on EMC Interface Property Characterization Using Cohesive Zone Modeling Method** ................................................................. 1109
Xiaosong Ma, Xianmin Huang, G.Q. Zhang

F-96  **Research on Silk screen printing conductive ink RFID and measurement** ........................................ 1114
Song Li, Zhou Ru

F-97  **Construction Analysis for Inherent Reliability Evaluation of Surface Acoustic Wave Filters** .... 1118
Hong-Zhi Liu, Xin Liu, Yun-Fei En, Yun Huang, Ping Lai

F-98  **Up-screening and Qualification of Plastic Encapsulated Microcircuits in High Reliability Applications** ..................................................................................... 1122
Shaohua Yang, Tao Ning

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### Session G -- Solid State Lighting Packaging & Integration

G-01  **The effects of humidity and temperature aging test on flexible packaging LED module** .......... 1126
Chunjing Hang, Jingming Fei, Yanhong Tian, Wei Zhang, Chunqing Wang, Susan Zhao, Jo Caers

G-02  **A Study of the Functions of a Novel Ripple TIR Lens** .............................................................. 1130
Shuiming Li, Fei Chen, Shuang Zhao, Zhili Zhao, Sheng Liu, Kai Wang

G-03  **Integrated LED module for local dimming with lower computational complexity and higher performances in LED backlight** ........................................... 1134
Zong Qin, Sheng Liu

G-05  **Conformal phosphor coating for phosphor-converted white LEDs on basis of dispensing process** .............................................................................................................. 1138
Huai Zheng, Yiman Wang, Xing Fu, Xiaobing Luo, Sheng Liu

G-06  **Junction Temperature Estimation for Multiple Light Emitting Diodes Based on Surface Point Measurement** ...................................................................................... 1142
Xing Fu, Xiaobing Luo

G-07  **System Packaging of Thousands Watt High Power LEDs with Heat Pipe-Fin Air Cooling System: Design and Manufacturing** ...................................................... 1146
Xing Fu, Zhangming Mao, Xiaobing Luo

G-08  **Design of double freeform-surface lens by distributing the deviation angle for light-emitting diode uniform illumination** .......................................................... 1150
Run Hu, Zhiqiang Gan, Xiaobing Luo

G-10  **Influence of rapid thermal cycling on optical property and microstructure of high power LED** ...................................................................................................................... 1154
G-11 Direct Bonding of Alumina Substrate with Copper Heat Sink in Air Assisted by Ultrasonic vibrations for High Power LEDs Devices .......................................................... 1158
Hongjun Ji, Xiao Cheng, Hao Chen, Mingyu Li, Qingtao Li

G-14 Study on LED devices Step-stress Accelerated degradation test ........................................ 1162
Junchao Wang, Xiaosong Ma

G-16 A multivariate system reliability estimation method based on step stress accelerated degradation testing ........................................................................................................ 1166
Hongliang Jia, Miao Cai, Daoguo Yang

G-17 A Novel Wafer Level Packaging for White Light LED .......................................................... 1170
Ye Xie, Dong Chen, Li Zhang, KH Tan, CM Lai

G-19 A Novel Lens for LED Airport Runway Centerline Lamp .................................................. 1175
Fei Wang, Chuangang Ji, Xiang Gao, Sheng Liu

G-20 Mechanical lock design for LED silicone lens with silicon substrate ........................................ 1179
Jiaojiao Yuan, Sheng Liu, Zhicheng Lv, Shuai shi, Yaping Lv, Jing fang, Shengwei Jiang, Can Gao, Xuefang Wan

G-21 Reliability test and failure analysis of high-brightness LEDs from Cree under the various injection currents ........................................................................................................ 1184
W. Liu, N. Li, P. Lei, B.B. Zou, P. Jin

G-22 Preparation of Phosphor Glass via Screen Printing Technology and Packaged Performance for LEDs .......................................................................................................................... 1189
Liang Yang, Mingxiang Chen, Sheng Liu, Shenjun Zhou

G-23 Research on Direct Plated Copper Heat Spreader and Its Thermal Performances for High Power LED Packaging ........................................................................................................ 1193
Xuebin Zhang, Mingxiang Chen, Ziliang Hao, Sheng Liu

G-25 High Quality & Low Thermal Resistance Eutectic Flip Chip LED Bonding ........................................ 1197
Ngai-Sze LAM, Chi-Yung LEE, Ming-Yeung WAN, Dewen TIAN, Ming LI

G-26 Reduction of Phosphor Particle Segregation Effects on the CIE & Spatial CIE Distribution of LED Packages ...................................................................................................................... 1202
ASM Dispensing Team

G-27 A reliability analysis method for LED Luminaires based on step stress accelerated degradation test ........................................................................................................................................ 1207

G-29 Experimental Characterization of Adhesion Strength between the Silicone Encapsulant and the Bottom of a SMD LED Leadframe Cup ........................................................................ 1212
Session H -- Emerging Technologies

H-01 Laser-induced Self-propagating Reaction in Ti/a-Si Multilayer Films .................................................. 1227
Mei Zhu, Rong An, Chunging, WangXinyao Fu,

H-02 Research on Simulation and Experiment of the Extrusion Process of High Conductivity Aluminum Alloy for Electronic Packaging ................................................................. 1231
FU Jinlong, WANG Kaikun, WANG Yuanning, WANG Yu, HE Xukun

H-03 Electric-thermo-mechanical Analysis of TSV under High Current Stressing ................................. 1235
Ming Xiao, Fengshun Wu, Hui Liu, Weisheng Xia

H-04 Fabrication of a Novel Handheld Actuator for Use in Wireless Capsule Endoscopy .................. 1240

H-06 Analysis of Thermal Cycling Testing for a 3D Integrated Package with Inter-Chip Microbumps ................................................................................................................................. 1243
Qiang Wang, Weidong Xie, Mudasir Ahmad

H-08 Closed-Form Expression for Capacitance of Tapered Through-Silicon-Vias Considering MOS Effect .......................................................... 1250
Fengjuan Wang, Yintang Yang, Zhangming Zhu, Xiaoxian Liu, Yan Zhang

H-09 Reduction of Signal Reflection Caused by TSV Insertion in Three-Dimensional On-Chip High Speed Interconnect Lines ................................................................. 1255
Xiaoxian Liu, Zhangming Zhu, Yintang Yang, Fengjuan Wang, Yan Zhang

H-10 Effects of Thermal Contact Resistance and Thomson Heating on the Outputs of Solar Thermoelectric Power Generation System ................................................................. 1260
Bimrew Tamrat Admasu, Xiaobing Luo

H-11 Novel Two-Dimensional EBG Structure Used to Suppress Simultaneous Switching Noise ...... 1264
Liuping Wang, Liqiang Cao, Lixi Wan

H-13 Polyl synthesis of silver nanowires with metal ions mediated .................................................. 1268
Ding Su, Tian Yanhong, He Xiaobin

H-15 Copper Filling by Electroplating for High Aspect Ratio TSV ............................................................ 1271
Yongfu Liu, Daowei Wu

H-16 Growth mechanism of Cu-Sn full IMC joints on polycrystalline and single crystal Cu substrate
Rui Zhang, Yanhong Tian, Baolei Liu, Chunjin Hang

H-18 Structure-Air Damping Coupling Analysis of Micromachined Gyroscope
Weihui Wang, Zhang Luo, Qiang Dan, Yong Xu, Sheng Liu

H-19 Simulation model and it’s sharp tuning for SiO2 Thin Film Transmission line
Wenbin Chen, Xianmin Huang, Xiaosong Ma, Miao Cai, Daoguo Yang

H-20 Modeling of a MEMS-based display device with Electric-Mechanical Coupling
FANG Wenxiao, HUANG Qinwen

H-21 Flexible ZnO Nanogenerator for Mechanical Energy Harvesting
Yanbiao Chu, Lixi Wan, Guowei Ding, Peng Wu, Delong Qiu, Jie Pan, Huimin He

H-22 Thermo-mechanical reliability study for 3D package module based on flexible substrate
Fengze Hou, Xia Zhang, Xueping Guo, Huiqin Xie, Yuan Lu, Liqiang Cao, Lixi Wan

H-23 The design and experiment research on two-phase flow dispenser
Jinsong Zhang, Guowei Xiao, Guiren Huang, Jianhua Zhang

H-24 Wafer level packaging for GaAs optical detector using through wafer grooves (TWG) fabricated by mechanical dicing and wet etching
Jiaotuo Ye, Shuangfu Wang, Chunsheng Zhu, Gaowei Xu, Le Luo

H-26 Hollow TSV VS Solid TSV and the Effect of Medium Filling in the Hollow TSV
Ning Jianye, Miao Min, Li Zhensong, Li Qinghai